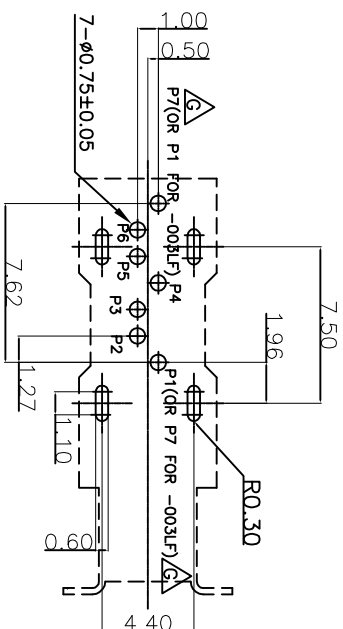
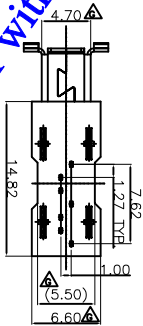
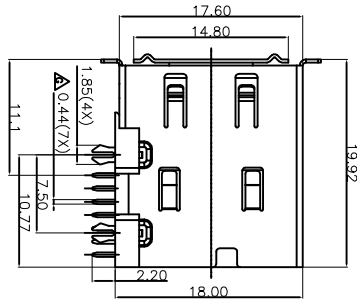
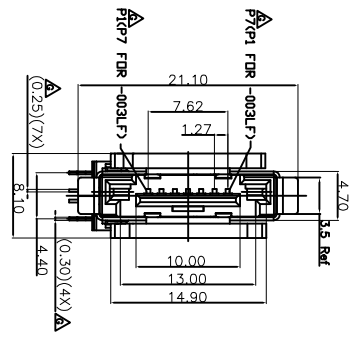


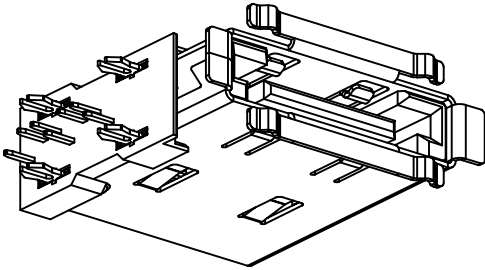
PRODUCT NO.
10074141-001LF
10074141-003LF



RECOMMEND P.C.B. BOARD LAYOUT
PCB TOLERANCE:±0.05

- NOTES:
1. MATERIAL: HOUSING:THERMAL/PLASTIC HIGH TEMP WITH 30% G/F U194 V-0
 2. FINISH: 500" MIN. NICKEL UNDERPLATING OVER ALL SHELL/BOARD LOOK:500" MIN. NICKEL PLATING OVER ALL IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB
 3. THE HOUSING WILL WITHSTAND TO 280C FOR 10 SEC
 4. PRODUCT SPEC : GS-12-386
 5. PACKING SPEC : GS-14-1109
 6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- PACKING: TRAY PACKING
BLANK: TRAY PACKING
1. 150" GOLD PLATING
2. 20" G/F GOLD PLATING
3. 150" GOLD PLATING WITH NEW PINOUT ASSIGNMENT

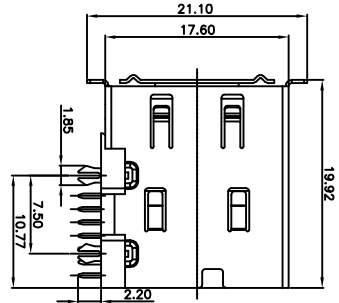
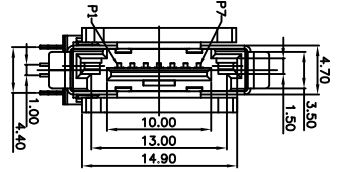
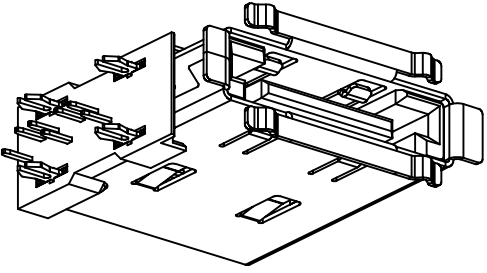
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PIN DEFINITION

ESATA	NAME	TYPE
P1	GND	GND
P2	A+	A+
P3	A-	A-
P4	GND	GND
P5	B-	B-
P6	B+	B+
P7	GND	GND

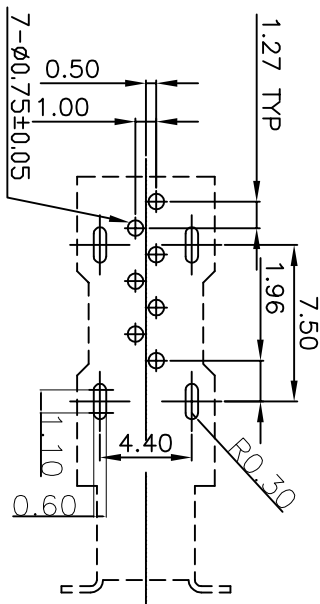
mat'l. code	14	surface	ISO 1302	ISO 406	ISO 150	projection	100	product family	533				
ltr	ecn no	dr	date	tolerances unless otherwise specified	angles	linear	scale	2:1					
A	107-1074	SLN	2007-05-23		.XX±0.38								
B	108-1082S	SLN	2008-04-28		.XX±0.25								
C	110-0184S	SLN	2010-12-14		.XXX±0.100								
D	T-00544QS	SLN	2011-08-31										
E	EX-S-007881	HKL	2011-10-17										
F	EX-S-0118781	HKL	2012-06-08										
G	EX-S-23468	HKL	2016-03-03										
Sheet	Revision	G	G	107109	111113	115117	119121	123125	127129	131133	135137	139	
Index	Sheet	1	2	3	106108	110112	114116	118120	122124	126128	130132	134136	138



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PIN DEFINITION

ESATA	NAME	TYPE
P1	GND	A+
P2	A+	A-
P3	A-	GND
P4	GND	B-
P5	B-	B+
P6	B+	GND
P7	GND	



P.C. BOARD MOUNTING DIMENSIONS T=1.60mm
PCB TOLERANCE: ±0.05

- NOTES:
1. MATERIAL: HOUSING: THERMAL PLASTIC HIGH TEMP WITH 30% G/F U194 V-0 COLOR: BLACK CONTACT: COPPER ALLOY SHELL/BOARD LOCK: COPPER ALLOY
 2. CONTACT: GOLD PLATING ON CONTACT AREA 100µ" MIN. WATT TIN PLATING ON SOLDERMILLS 50µ" MIN. NICKEL UNDERPLATING OVER ALL BOARD LOCK: 50µ" MIN. NICKEL PLATING OVER ALL SHELL/BOARD LOCK: 50µ" MIN. NICKEL PLATING OVER ALL
 3. IN A WAVE SOLDER APPLICATION WITH A 1.5MM PCB
 4. PRODUCT SPEC : GS-12-398
 5. PACKING SPEC : GS-14-1109
 6. PRODUCT NUMBERING: 10074141 - 0 0 0 LF LEAD FREE
- PAKING: BLANK: TRAY PACKING
1: 15µ" GOLD PLATING
2: 6/7 GOLD PLATING
6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION

mat'l. code	14	surface	sg	tolerance	projection	product family
lfr	ecm no	dr	date	ISO 1302	ISO 406	ISO 100
A	107-1074S	LIN	2007-05-23	tolerances unless otherwise specified	MM	533
B	108-1082S	LIN	2008-04-28	angle	MM	E-SATA_UP_RIGHT
C	110-0184S	LIN	2010-12-14	linear	MM	DIP_TYPE
D	T-00544QS	LIN	2011-08-31	σ±Z	SCALE 2:1	
E	EX-S-0078R	HKL	2011-10-17	STERLING	LIN	2007-05-21
F	EX-S-0118R	HKL	2012-06-08	HKLIM		2016-03-03
G	EX-S-234W	HKL	2016-03-03	KPTAY		2016-03-03

sheet	revision	sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138
index	sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138	



Amphenol
FCI

type PRODUCT-CUSTOMER_DWG Drawing

dwg no 10074141 sheet 2 of 3 size A3

title E-SATA_UP_RIGHT DIP_TYPE

product family 533

projection 100

tolerance

ISO 1302

ISO 406

ISO 100

tolerances unless otherwise specified

angle

linear

σ±Z

SCALE 2:1

STERLING

LIN

2007-05-21

HKLIM

2016-03-03

KPTAY

2016-03-03

121

123

125

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137

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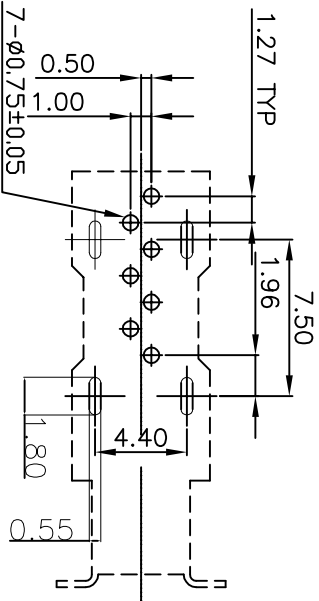
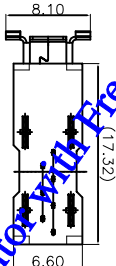
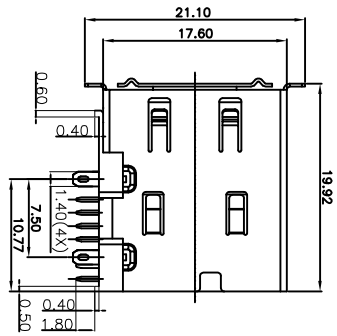
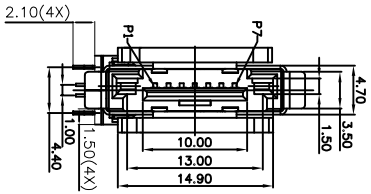
131

133

135

137

139



P.C.B. BOARD MOUNTING DIMENSIONS T=1.60mm
PCB TOLERANCE: ±0.05

PIN DEFINITION	
ESATA	NAME TYPE
	P1 GND
	P2 A+
	P3 A-
	P4 GND
	P5 B-
	P6 B+
	P7 GND

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mat'l. code	14	surface sg	tolerance	projection	product family
ltr ecn no	dr date	ISO 1302	ISO 406	ISO 100	533
A	107-1074S.LIN	2007-05-23	XX±0.38	MM	E-SATA_UP_RIGHT
B	108-1082S.LIN	2008-04-28	XX±0.25	MM	DIP_TYPE
C	110-0184S.LIN	2010-12-14	.XXX±0.100	scale 2:1	
D	T-00544QS.LIN	2011-08-31	STERLING.LIN	2007-05-24	
E	EX-S-00781	HKL	2011-10-17	ENG	
F	EX-S-01187	HKL	2012-06-08	CH	
G	EX-S-2340	HKL	2016-03-03	DPD	
Sheet	Revision	1	2	3	107 109 111 113 115 117 119 121
Index	Sheet	G	G	G	106 108 110 112 114 116 118 120 122 124 126 128 130 132 134 136 138

- NOTES:
1. MATERIAL: THERMOPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0
 2. FINISH: CONTACT: COPPER ALLOY; SHELL/BOARD LOCK: COPPER ALLOY
 3. CONTRACT/GOLD PLATING ON CONTACT AREA
 4. BOARD LOCK: 50μ" MIN. NICKEL UNDERPLATING OVER ALL SHELL/BOARD LOCK; 50μ" MIN. NICKEL PLATING OVER ALL
 5. IN A WAVE SOLDER APPLICATION WITH A 1.5MM PCB
 6. PRODUCT SPEC: 05-12-386
 7. PACKING SPEC: 05-14-1109
 8. PRODUCT NUMBERING: 10074141 - 2 0 X X X LF - LEAD FREE
6. A SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- 2: LAYOUTS
1: 15μ" GOLD PLATING
2: 0.7μ" GOLD PLATING
PACKING: TRAY PACKING
BLANK: TRAY PACKING